		CUSTOMER		ENGINEER	
		TEXAS INSTRUMENTS		YOON LEE	
		BOARD NAME : TYPE C DOCK_REVB			
		ASSEMBLY DRAWING (TOP SIDE)			
APPROVALS	DATE	SIZE	KSID NO.	JOB NO.	REV.
DRAWN: SWG	05-01-15	D	15991	126216	1.0
RELEASED: SWG	05-13-15				
DO NOT SCALE DRAWING		SCALE	NONE	SHEET 1 OF 2	

8

7

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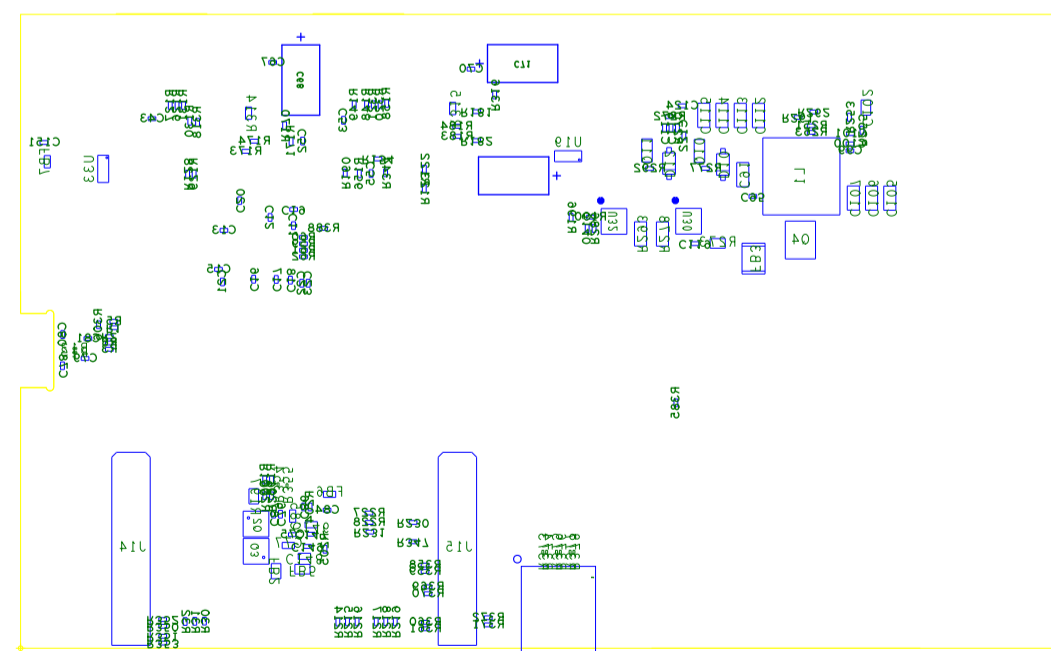
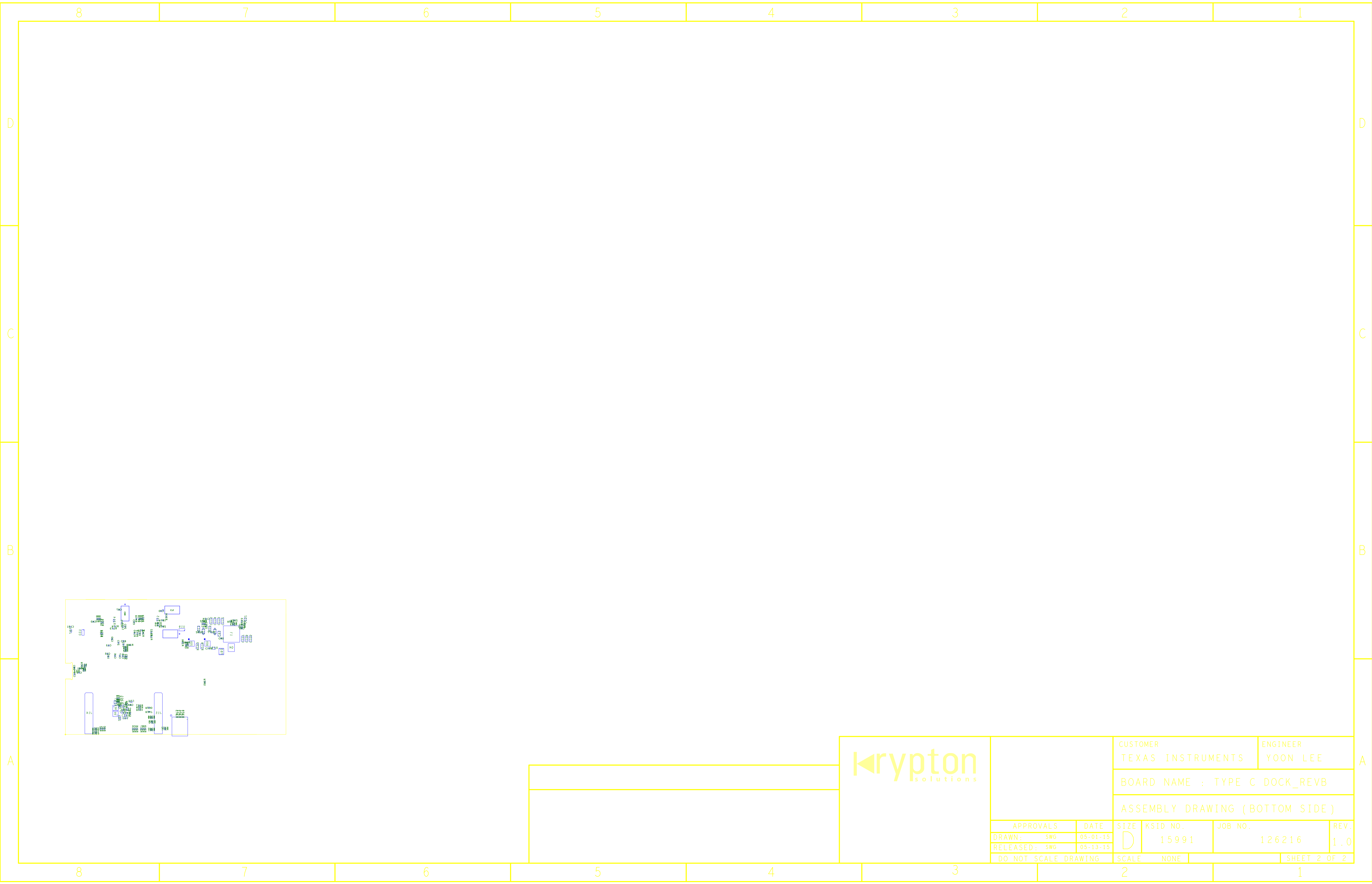
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1



	APPROVALS		DATE	SIZE	KSID NO.	JOB NO.	REV.
	DRAWN: SWG		05-01-15	D	15991	126216	1.0
	RELEASED: SWG		05-13-15				
DO NOT SCALE DRAWING			SCALE	NONE		SHEET 2 OF 2	

CUSTOMER	ENGINEER
TEXAS INSTRUMENTS	YOON LEE

BOARD NAME : TYPE C DOCK_REVB

ASSEMBLY DRAWING (BOTTOM SIDE)

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